

Preface

Dear Distinguished Delegates and Guests,

The Organizing Committee of ICMSET 2013 warmly welcomes you to the 2013 2nd International Conference on Material Science and Engineering Technology (ICMSET 2013), held on November 16 -17, 2013 in London, the United Kingdom. ICMSET 2013 is co-sponsored by Science and Engineering Institute, USA.

The conference is aimed at providing a platform for all of you to present leading-edge work in the fields of Advanced Materials Research. More than 160 papers were submitted to ICMSET 2013 and around 73 papers are accepted for the conference after peer reviewed by reviewers drawn from the scientific committee, external reviewers and editorial board depending on the subject matter of the paper. Reviewing and initial selection were undertaken electronically. After the peer-review process, the submitted papers were selected on the basis of originality, significance, and clarity for the purpose of the conference. The selected papers and additional late-breaking contributions to be presented as lectures will make an exciting technical program. The conference program is extremely rich, featuring high-impact presentations. .

The proceeding records the fully refereed papers presented at the conference. The main conference themes and tracks are Material Science and Engineering Technology. The main goal of ICMSET 2013 is also to provide international scientific forums for exchange of new ideas focus on Material Science and Engineering Technology.

We would like to thank the program chairs, organization staff, and the members of the program committees for their work. Thanks also go to all those who have contributed to the success of ICMSET 2013.

Hopefully, all participants and other interested readers benefit scientifically from the proceedings and also find it stimulating in the process.

We hope all of you have a unique, rewarding and enjoyable week at ICMSET 2013 in London.

With our warmest regards,

Prof. K.M.Gupta, Motilal Nehru National Institute of Technology, India

London, the United Kingdom

November 16 -17, 2013

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